

Title (en)

TITANIUM COPPER PLATE, PRESSED PRODUCT, AND PRESSED-PRODUCT MANUFACTURING METHOD

Title (de)

TITANKUPFERPLATTE, GEPRESSTES PRODUKT UND VERFAHREN ZUR HERSTELLUNG VON GEPRESSTEN PRODUKTEN

Title (fr)

PLAQUE EN TITANE ET CUIVRE, ET ARTICLE FAÇONNÉ À LA PRESSE AINSI QUE PROCÉDÉ DE FABRICATION DE CELUI-CI

Publication

**EP 3845676 A4 20220518 (EN)**

Application

**EP 19854088 A 20190531**

Priority

- JP 2018161952 A 20180830
- JP 2019021863 W 20190531

Abstract (en)

[origin: EP3845676A1] Provided is a titanium copper plate which is a non-mill hardened material of titanium copper which is subjected to a heat treatment after pressing and which has good springiness and dimensional stability after the heat treatment. The titanium copper plate contains from 2.0 to 4.5% by mass of Ti, the balance being copper and inevitable impurities, wherein the titanium copper plate has a tensile strength in a rolling parallel direction of 750 MPa or more, and a conductivity of from 4.0 to 8.0% IACS, and wherein the titanium copper plate has a spring limit value of 800 MPa or more in the rolling parallel direction when subjected to a heat treatment at 400 °C for 2 hours, and a thermal expansion/contraction ratio of 100 ppm or less in the rolling parallel direction when subjected to a heat treatment at 400 °C for 2 hours.

IPC 8 full level

**C22C 9/00** (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)

**C21D 9/46** (2013.01 - KR); **C22C 9/00** (2013.01 - EP KR); **C22F 1/00** (2013.01 - EP); **C22F 1/08** (2013.01 - EP KR)

Citation (search report)

- [X] US 2010101687 A1 20100429 - SUGAWARA YASUTAKA [JP]
- [A] JP 4001491 B2 20071031
- [A] US 2002157741 A1 20021031 - YAMAMOTO MICHIHARU [JP], et al
- [A] JP 5368581 B2 20131218
- [A] JP 2016050341 A 20160411 - JX NIPPON MINING & METALS CORP
- See references of WO 2020044699A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 3845676 A1 20210707**; **EP 3845676 A4 20220518**; CN 112601828 A 20210402; CN 112601828 B 20220419; JP 2020033617 A 20200305; JP 6629400 B1 20200115; KR 102455771 B1 20221018; KR 20210038638 A 20210407; TW 202009309 A 20200301; TW I692535 B 20200501; WO 2020044699 A1 20200305

DOCDB simple family (application)

**EP 19854088 A 20190531**; CN 201980054988 A 20190531; JP 2018161952 A 20180830; JP 2019021863 W 20190531; KR 20217005796 A 20190531; TW 108121322 A 20190619